



### DESIGN QUALIFICATION APPROVAL & ENVIRONMENTAL SPECIFICATION

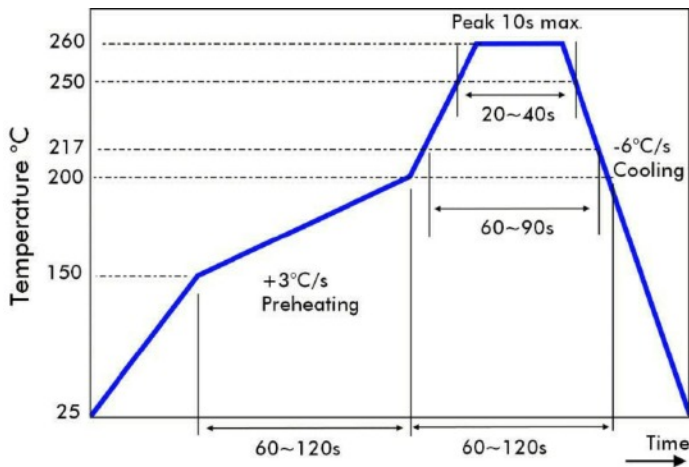
Thermal Shock:	MIL-STD-883F Method 1011.9 Condition B
Mechanical Shock:	MIL-STD-883K Method 2002.5 Condition D
Vibration:	MIL-STD-883F Method 2007.3
High Temp Storage:	MIL-STD-202 Method 108
Moisture Resistance:	JIS C7021:B-11
Seal:	Fine leak not to exceed 1x10 <sup>-8</sup> mB litres of He leakage.
Solderability:	MIL-STD-883E Method 2003.7

### OPTIONAL SCREENING

Screening in accordance with MIL-O-55310C Class B  
All devices are 100% tested to the following conditions:

Temp Cycling:	-55C to +125C, 10 cycles.
Constant Acceleration:	49000m/s <sup>2</sup> for 1 min in XY plane.
Seal:	Fine leak not to exceed 1 x 10 <sup>-8</sup> mB litres of He
Dynamic Burn-in:	125C for 168 hrs
Electrical Test:	Frequency, output waveform, output Voltage input current.

### SOLDER TEMPERATURE PROFILE



### ORDERING/PART NUMBER GENERATION

Example: **20.000MHz EQXO-75BM050UMTAC**

Frequency

Series Designation

Stability:

050 = ±50ppm

075 = ±75ppm

100 = ±100ppm

(For tighter stability, ask)

LVC MOS

Operating Temperature Range:

I = -40° to +85°C

M = -55° to +125°C

Tristate

Supply Voltage:

A = 3.3 Volts

B = 2.5 Volts

Optional Crystal Pre-Ageing:

Left Blank = Standard (additional 96hr oven pre-aged)

C = Custom Crystal Pre-age (contact sales)